



COPY OF PAPERS
ORIGINALLY FILED

2827

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Salman Akram
Serial No.: 09/853,111
Filed: May 10, 2001
For: Method of Fabricating Mounted
Multiple Semiconductor Dies In
A Package (As Amended)



§ Group Art Unit: 2827
§
§
§ Examiner: A. Chambliss
§
§
§ Atty. Dkt. No.: MCT.0012D1US
§ (97-0141)

TECHNICAL CENTER 800

AUG-6 2002

RECEIVED

#8/D

And
J. McNeill
8/8/02

Box Non-Fee Amendment
Commissioner for Patents
Washington DC 20231

REPLY TO PAPER NO. 5

Sir:

In response to the office action mailed July 8, 2002, please amend the above-referenced patent application as follows:

IN THE DRAWINGS

Attached is a submission of formal drawings.

IN THE CLAIMS

Please amend claim 15 as follows:

15 (Three Times Amended). A method for mounting multiple semiconductor dies on a single leadframe having fingers, comprising:

stacking at least two semiconductor dies having substantially the same rectangular dimensions on top of one another such that one of said dies is mounted on top of the leadframe fingers and the other of said dies is mounted on the die mounted on the leadframe fingers; and wire bonding each of said semiconductor dies to the same leadframe fingers.

Date of Deposit: July 24, 2002
I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated, above and is addressed to the Commissioner for Patents, Washington DC 20231.

Cynthia L. Hayden
Cynthia L. Hayden